

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#2/A
13 May 03
P. Tall

In re application of

Hui ZHONG, et al.

Appln. No.: based on PCT/JP00/05044

Group Art Unit: Not yet designated

Confirmation No.: Not yet designated

Examiner: Not yet designated

Filed: February 11, 2002

February 11, 2002

For: MULTILAYERED PRINTED CIRCUIT BOARD, SOLDER RESIST COMPOSITION,
MULTILAYERED PRINTED CIRCUIT BOARD MANUFACTURING METHOD, AND
SEMICONDUCTOR DEVICE

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to examination, please amend the above-identified application as follows:

IN THE SPECIFICATION:

Amend the specification by inserting before the first line the sentence:

A¹
This is a National stage entry under 35 U.S.C. § 371 of PCT Application No.
PCT/JP00/05044 filed July 28, 2000; the above noted application is hereby incorporated by
reference.

IN THE CLAIMS:

The claims are amended as follows:

A²
4. (amended) The multilayered printed circuit board according to claim 1,
wherein said solder resist layer contains an elastomer.